Product Document





Datasheet

DS001056

Mira220

1/2.7" 2.2MP NIR Enhanced Global Shutter Image

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1 General Description

Mira220 is a 2.2 MP NIR enhanced global shutter image sensor with a small 2.79 µm pixel size. It has excellent low light sensitivity made possible by a state-of-the-art stacked BSI technology. With an effective resolution of 1600 x 1400 and a maximum bit depth of 12 bits, the sensor supports on-chip operations like external triggering, windowing, horizontal or vertical mirroring. The maximum frame rate is 90 fps at full resolution and bit depth. The sensor has a MIPI CSI-2 interface to allow easy interfacing with a plethora of processors and FPGAs. On-chip registers can be accessed via the standard I²C interface for easy configuration of the sensor.

Due to its small size, configurability and high sensitivity both in visual as well as NIR, the Mira220 is well suited for 2D and 3D applications, which include Active Stereo Vision, Structured Light Vision for Robotics and AR/VR. High sensitivity in NIR enables increased measurement range and allows overall system power consumption optimization which is key for battery powered consumer and industrial applications.

1.1 Key Benefits & Features

Figure 1: Added Value of Using Mira220

| Benefits | Features |
|---|---|
| Compact size with high resolution and bit depth | 1/2.7" 1600x1400 8/10/12-bit 2.79 µm |
| High speed applications | 90 fps global shutter with CDS |
| Use in low light conditions | High sensitivity |
| Compact size | Small die size achieved via state-of-the-art stacked BSI technology |
| NIR enhanced with high sensitivity | Class leading QE at 940 nm combined with high sensitivity. Industry leading PLS at 940 nm |
| On chip noise reduction | Digital CDS and row noise correction |
| Reduced off-chip processing | On chip defect pixel detection and correctionOn chip image statistics generation |
| Multiple Variants | Available as Mono, RGB or RGBIR variant. Orderable with AR coated or plain glass and protective film |
| Extended battery operation | Low power consumption |



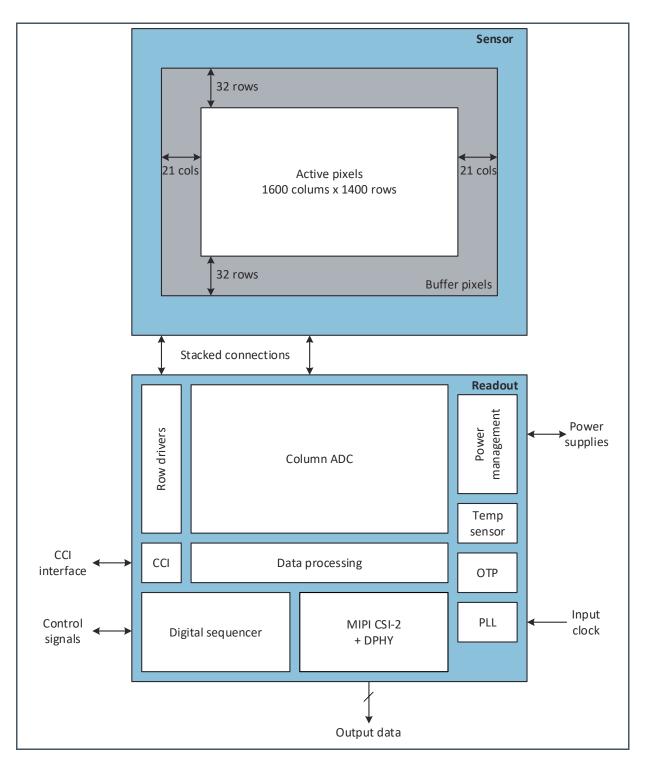
1.2 Applications

- Mobile Facial Authentication
- Active Stereo Vision
- Smart Home Appliances
- QR Readers.
- Automatic Identification and Data Capture (AIDC).
- AR/VR
- Structured Light Vision
- Drones
- Smart Wearable Devices
- SLAM for Robotics



1.3 Block Diagram

Figure 2: Functional Blocks of Mira220





2 Typical Operating Characteristics

2.1 Electro-Optical Characteristics

Below are the typical electro-optical specifications of Mira220.

Figure 3:

Optical Features of Mira220

| Parameter | Value | Remark |
|----------------|--------------------------|--|
| Active Pixels | 1600 (H) × 1400 (V) | |
| Pixel Pitch | 2.79 × 2.79 μm² | |
| Optical Format | 1/2.7" | |
| Pixel Type | BSI global shutter | With fixed pattern noise correction and reset (kTC) noise canceling by correlated double sampling (CDS) coupled with high sensitivity. |
| Shutter Type | Pipelined global shutter | Exposure of next image during readout of the previous image. |

Figure 4:
Typical Electro-Optical Characteristics

| Parameter | Value | Remark |
|--|--------------------------|---|
| Supported Lens Chief Ray Angles (CRA) | 0° to 30° | Extra wide acceptance angle of the Mira220 pixel means any lens profile with these CRA values would provide decent performance. |
| Quantum Efficiency (QE) Mono | 95 / 56 / 36 % | 550 / 850 / 940 nm |
| Quantum Efficiency (QE) RGB and RGBIR | 76 / 85 / 80 / 56 / 36 % | 450 / 530 / 605 / 850 / 940 nm |



2.2 Functional Characteristics

Figure 5: Functional Characteristics

| Parameter | Value |
|---------------------------|--|
| | 12-bit |
| Bit Depth | 10-bit |
| | 8-bit |
| Timing Generation | On-chip |
| Programmable Registers | Sensor parameters. e.g. Window coordinates, Timing parameters, and Exposure time |
| | 168 mW Active 30fps |
| Power Consumption | 40 mW Idle |
| | 4 mW Sleep |
| Data Interface Standard | MIPI CSI-2 |
| Data internace standard | DPHY |
| MIPI Outputs | 2 Data |
| | 1 Clock |
| Output Interface Bit Rate | 1.5 Gbit/s |
| Frame Rates | 90 fps |
| Black Sun Protection | Yes |
| Temperature Sensor | Yes |
| Context Switching | Two register contexts |



Revision Information 3

| Changes from previous version to current revision v2-00 | Page |
|---|------|
| Updated General Description | 3 |
| Updated Figure 1 | 3 |
| Updated Figure 4 | 6 |
| Updated Figure 5 | 7 |

- Page and figure numbers for the previous version may differ from page and figure numbers in the current revision.
- Correction of typographical errors is not explicitly mentioned.